Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP MP9 Model 9000 Digital Signage Player

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon 65W EPS</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC cable</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>DC cable</td>
<td>1</td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>#1 Torx Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>#2 Slotted Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>#3 Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect the AC adapter cable.(see Figure 1 below)
2. Remove the access panel.(see Figure 2-3 below)
3. Remove the front bezel.(see Figure 4-5 below)
4. Remove HDD and HDD cable.(see Figure 6-9 below)
5. Remove HDD cage and Hood sense cable.(see Figure 10-12 below)
6. Remove Memorys.(see Figure 13-14 below)
7. Remove CPU HeatSink.(see Figure 15-16 below)
8. Remove system fan.(see Figure 17-19 below)
9. Remove PCIE cards.(see Figure 20-24 below)
10. Remove speaker,CPU and battery.(see Figure 25-31 below)
11. Remove MB.(see Figure 32-33 below)
12. Remove antenna cover and antenna cables.(see Figure 34-38 below)
13. Remove the covers.(see Figure 39-41 below)
14. Remove the PCA, and disconnect the cables.(see Figure 42-45 below)
15. Remove the Electrolytic Capacitors.(see Figure 46)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Disconnect the AC adapter cable.

Figure 2 Remove the thumb screw.

Figure 3 Remove the Access Panel

Figure 4 Loose the anchor point of front bezel.

Figure 5 Remove the Front Bezel.

Figure 6 Disconnect HDD SATA cable.
Figure 7 Disconnect HDD Power cable.

Figure 8 Loose the HDD latch and remove HDD.

Figure 9 Disconnect the cable from the HDD.

Figure 10 Loose the screw from HDD cage.

Figure 11 Disconnect the hood sense cable.

Figure 12 Take out the HDD cage and remove hood sense cable.
Figure 13: Loose the fixed feature of memory.

Figure 14: Remove the Memory from the board.

Figure 15: Loose the screw of CPU HeatSink.

Figure 16: Remove the CPU HeatSink.

Figure 17: Disconnect the system fan cable.

Figure 18: Loose the screws of system fan cable.
<table>
<thead>
<tr>
<th>Figure 19</th>
<th>Remove the system fan.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Figure 20</td>
<td>Disconnect the antenna cable.</td>
</tr>
<tr>
<td>Figure 21</td>
<td>Loose the WLAN card screw.</td>
</tr>
<tr>
<td>Figure 22</td>
<td>Remove the WLAN card.</td>
</tr>
<tr>
<td>Figure 23</td>
<td>Loose SSD card screw.</td>
</tr>
<tr>
<td>Figure 24</td>
<td>Remove the SSD card.</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 25 Disconnect the speaker cable.

Figure 26 Remove the plastic screw.

Figure 27 Remove the Speaker.

Figure 28 Rotate the handle and open it up.

Figure 29 Remove the CPU from the board.

Figure 30 Pull the battery towards the chassis wall.

PSG instructions for this template are available at EL-MF877-01
Figure 31 Remove the battery from the system board.

Figure 32 Loose MB screw.

Figure 33 Remove the MB.

Figure 34 Loose the antenna cover hook.

Figure 35 Remove the antenna cover.

Figure 36 Loose the antenna cable tape.
Loose the antenna hook.

Remove the antenna.

Used Hammer and Slotted Screwdriver to destroy the Case (Use Delta EPS as an example).

Lift the cover off the PCBA.

Lift the cover off.

Remove the HeatSink from the board.
Figure 43 Remove the power cable from the board.

Figure 44 Remove the Socket from the board.

Figure 45 Remove the Socket from the board.

Figure 46 Remove the Electrolytic Capacitors.